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Dr. Kim is a packaging engineer of SK hynix. Since joining SK Hynix in 2005, he has been involved in packaging development division and developing advanced packaging technology such as TSV, Flip-chip bumping, FOWLP, etc. He holds about 50 US patents in the field of semiconductor packaging technology. He received the Ph.D. in the department of Material Science and Engineering from Korea Advanced Institute of Science and Technology (KAIST), Korea in 2005.